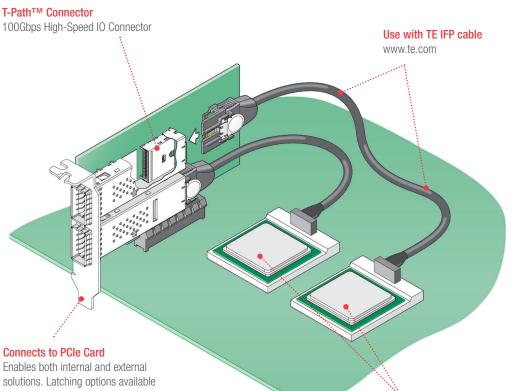
T-Path 100-Gbps Connector Solutions

The innovative T-Path 100-Gbps Connector Solution improves signal integrity and decreases latency by transmitting directly to an Intel processor and bypassing printed circuit board traces via an internal cable

Features and Benefits



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T-Path 100-Gbps Surface Mount Connector

Improved Signal Integrity

Improves Signal Integrity on high speed signals over a low loss internal cable versus the traditional design that uses lossy PCB traces

Connects directly to Intel Skylake Xeon and Knights Landing Xeon Phi processors (www.intel.com) Bypasses PCB traces. Improves signal integrity and performance

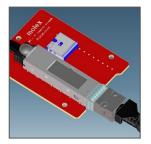
Applications

Telecommunications/Networking

- Supercomputers
- Servers
- Machine Learning
- Artificial Intelligence



Servers



T-Path Connector and Cage on Red Board

T-Path 100-Gbps Connector Solutions

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Specifications

REFERENCE INFORMATION

Packaging: Tray UL File No.: E29179 Mates With: Copper Cable Assemblies (Series 74757, 111040) Designed In: Millimeters

ELECTRICAL

Voltage: 30V Current (max.): 0.5A; power contacts 1.0A Contact Resistance (max.): 30 milliohms Dielectric Withstanding Voltage: 500V AC Insulation Resistance (min.): 1000 Megohms

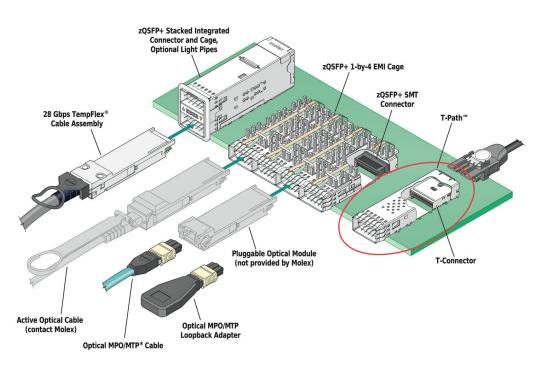
MECHANICAL

Mating Force: 0.75N per circuit Unmating Force: 0.25N per circuit Durability: 100 cycles for 30µ" Gold (Au) plating

PHYSICAL

Housing: Glass Filled, LCP, UL 94V-0 Heat Sink Clip: Stainless Steel Cage: Stainless Steel EMI Springs: Copper Alloy Contact: High-performance Copper Alloy Plating: .76µm min gold over 2.54 µm Nickel Contact Area — Gold Solder Tail Area — Tin over Nickel Underplating — Nickel Operating Temperature: -40 to +80°C

zQSFP Digital Product Board



Ordering Information

Series No.	Component
172604	Connector
	Cage for Heat Sink (Not Light Pipe Compatible)
	Cage (Neither Heat Sink nor Light Pipe Compatible)
100013	Heat Sink
	Heat Sink Clip

www.molex.com/link/tpath.html

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